



SOT1866-1

DIL-bent-SIL (special bent) power package; 27 leads (lead length 6.8 mm)

10 June 2016

Package information

1. Package summary

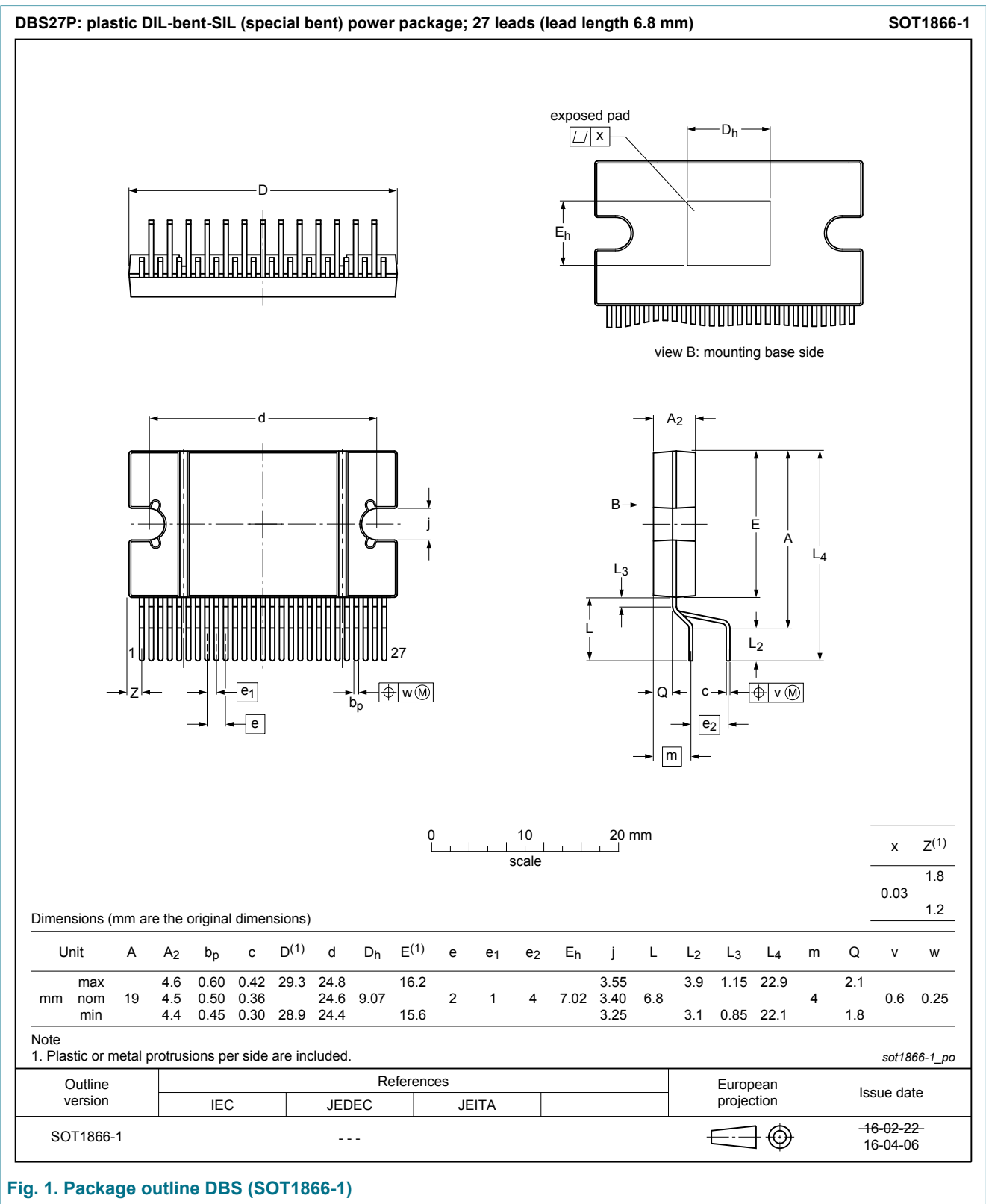
Terminal position code	S (single)
Package type descriptive code	DBS27P
Package type industry code	DBS
Package style descriptive code	DBS (DIL-bent-SIL)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	6-4-2016

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		28.9	-	29.1	29.3	mm
E	package width		15.6	-	15.9	16.2	mm
A	seated height		-	-	19	-	mm
e	nominal pitch		-	-	2	-	mm
n ₂	actual quantity of termination		-	-	27	-	



2. Package outline



3. Legal information

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